EX1: Center signal line over a grounded semiconducting substrate, with coplanar “ground straps,” 50 µm separation (W = 50 µm).
EX2: Center signal line over a grounded semiconducting substrate, with coplanar “ground straps,” 5 µm separation (W = 5 µm).

EX3: “Microstrip” signal line over a grounded semiconducting substrate:

EX4: Signal line with coplanar “ground straps,” 50 µm separation, no lossy substrate (W = 50 µm).
EX5: Signal line with coplanar “ground straps,” 5 µm separation, no lossy substrate (W = 5 µm):
EX1: Signal line over semiconducting substrate, coplanar “ground straps,” W = 50 μm.
EX2: Signal line over a semiconducting substrate, coplanar “ground straps,” W = 5 μm.
EX3: “Microstrip” signal line over a grounded semiconducting substrate.
EX4: Signal line with coplanar grounds, W = 50 μm, no lossy substrate.
EX5: Signal line with coplanar grounds, W = 5 μm, no lossy substrate.